

< L/S band internally matched power GaAs FET >

MGFS45B2527B

2.5 - 2.7 GHz BAND / 30W

DESCRIPTION

The MGFS45B2527B is an internally impedance-matched GaAs power FET especially designed for use in 2.5 – 2.7 GHz band amplifiers. The hermetically sealed metal-ceramic package guarantees high reliability.

FEATURES

Class AB operation Internally matched to 50(ohm) system

- High output power
- Po(SAT)=30W (TYP.) @f=2.5 2.7GHz
- High power gain GLP=12.5dB (TYP.) @f=2.5 – 2.7GHz

Distortion

EVM=1.0% (TYP.) @f=2.5 – 2.7GHz, Po=34dBm EVM=2.0% (TYP.) @f=2.5 – 2.7GHz, Po=37dBm

RECOMMENDED BIAS CONDITIONS

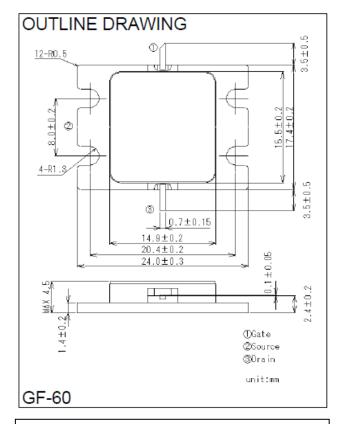
• VDS=12V • ID=0.9A • RG=10ohm

Absolute maximum ratings (Ta=25°C)

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Symbol	Parameter	Ratings	Unit					
VGDO	Gate to drain breakdown voltage	-15	V					
VGSO	Gate to source breakdown voltage	-10	V					
MAXID	Maximum drain current	10	А					
PT *1	Total power dissipation	78	W					
Tch	Cannel temperature	175	°C					
Tstg	Storage temperature	-55 to +150	°C					

*1 : Tc=25°C

Electrical characteristics (Ta=25°C)



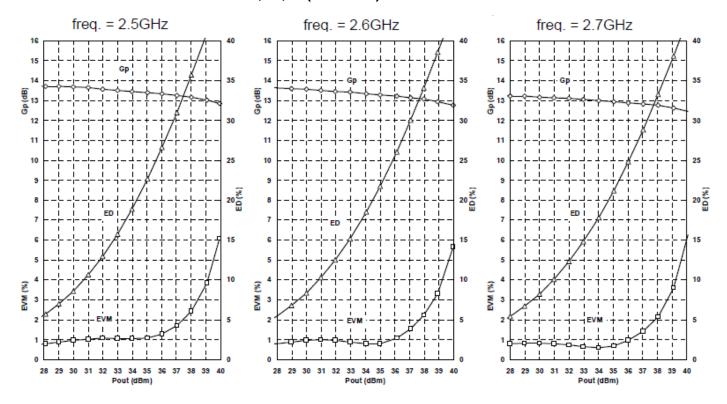
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Symbol	Parameter	Test conditions		Limits		
			Min.	Тур.	Max.	
VGS(off)	Gate to source cut-off voltage	VDS=3V,ID=100mA	-0.5	-	-3.0	V
Po(SAT)	Output Power	VDS=12V,ID(RF off)=0.9A	-	45	-	dBm
		f=2.5 – 2.7GHz				
GLP	Power Gain	VDS=12V,ID(RF off)=0.9A	10.0	12.5	-	dB
ID	Drain current	f=2.5 – 2.7GHz ,Pout=34dBm	-	1.2	1.5	А
EVM *2	Error Vector Magnitude		-	1.0	2.0	%
Rth(ch-c) *3	Thermal resistance	delta Vf method	-	1.2	1.9	°C/W

*2 :WiMAX Downlink, 64QAM-3/4, Channel Bandwidth:6MHz

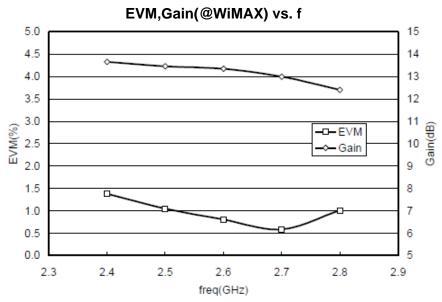
*3 :Channel-case

MGFS45B2527B TYPICAL CHARACTERISTICS



EVM,GP,ED(@WiMAX) vs. Pout

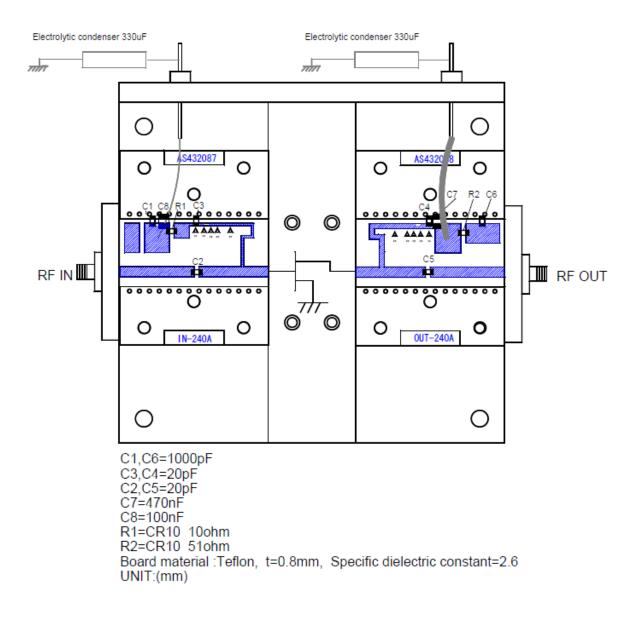
Test Condition Vds=12V,Idq=0.9A,Ta=25deg.C WiMAX:64QAM-3/4,Bw=6MHz



Test Condition

Vds=12V,Idq=0.9A,Pout=34dBm,Ta=25deg.C WiMAX:64QAM-3/4,Bw=6MHz

MGFS45B2527B RF TEST FIXTURE



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